

	Type	Hits	Search Text
1	BRS	164	wiring near3 (external adj terminal) and chip
2	BRS	68	wiring near3 (external adj terminal) and (transistor fet)
3	BRS	210	(transistor fet) near3 (guard adj ring)
4	BRS	25	((transistor fet) near3 (guard adj ring)) and wiring
5	BRS	5	electrodes near5 (metal adj wires) near5 (external adj electrodes)
6	BRS	134	(chip IC die) near3 (fet transistor) near5 wiring
7	BRS	4	(chip IC die) near3 (fet transistor) near5 wiring near5 (ground VSS)
8	BRS	0	wirings near5 (ground VSS)near5 (guard adj ring)
9	BRS	18	wirings near5 (ground VSS)near5 (electrodes (metal adj film\$2))
10	IS&R	1	("6399991").PN.
11	BRS	18	("4975758"   "5309012"   "5614744"   "5637900"   "5714784"   "5838050").PN.
12	BRS	0	6399991.URPN.
13	BRS	0	6399991.URPN.
14	BRS	18	("4975758"   "5309012"   "5614744"   "5637900"   "5714784"   "5838050").PN.
15	IS&R	14	((("5828110") or ("5187558") or ("5153699") or ("5834826") or ("5491358"))).PN.
16	BRS	470814	interlayer ad wires

	DBs	Time Stamp	Comments	Error Definition
1	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/06/24 10:50		
2	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/06/24 10:32		
3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/06/24 10:04		
4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/06/24 10:05		
5	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/06/24 10:33		
6	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/06/24 10:54		
7	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/06/24 10:55		
8	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/06/24 10:56		
9	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/06/24 10:57		
10	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/06/24 12:07		
11	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/06/24 12:06		
12	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/06/24 12:07		
13	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/06/24 12:07		
14	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/06/24 12:07		
15	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/06/24 13:08		
16	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/06/24 13:08		

	Type	Hits	Search Text
17	BRS	527	(interlayer ad wires) and (guard adj ring)
18	BRS	368	((interlayer ad wires) and (guard adj ring)) and wires
19	BRS	5	((interlayer ad wires) and (guard adj ring)) and wires) and (external adj electrodes)
20	BRS	4	(package adj core) and (heat adj sink)
21	BRS	985	build adj up adj surface
22	BRS	25	(build adj up adj surface) and (heat adj sink)
23	BRS	9	(build adj up adj layer) and (heat adj sink)
24	BRS	0	527/706,712,720.ccls. and (ic chip die)
25	BRS	1524	257/706,712,720.ccls. and (ic chip die)
26	BRS	444	(257/706,712,720.ccls. and (ic chip die)) and (plastic (encapsulant adj material))
27	BRS	3	((257/706,712,720.ccls. and (ic chip die)) and (plastic (encapsulant adj material))) and (build near3 layer)
28	BRS	143	257/700,758.ccls. and (heat adj (sink spreader element plug))
29	BRS	6517	257/706-707,712-713,717,720,723-724.ccls.
30	IS&R	5	((("6160311") or ("5250843"))).PN.
31	BRS	49	("4630096"   "4714516"   "4783695"   "4827328"   "4835704"   "4860166"   "4866508"   "4878991"   "4884122"   "4894115"   "4901136"   "4907062"   "4918811"   "4933042"   "5049980"   "5065282"   "5091769"   "5111278").PN.

	DBs	Tim Stamp	Comments	Error Definition
17	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/06/24 13:09		
18	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/06/24 13:09		
19	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/06/24 13:10		
20	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/06/24 17:32		
21	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/06/24 17:33		
22	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/06/24 17:38		
23	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/06/24 18:08		
24	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/06/24 17:45		
25	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/06/24 17:46		
26	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/06/24 17:52		
27	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/06/24 17:53		
28	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/06/24 18:25		
29	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/06/24 18:48		
30	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/06/24 20:04		
31	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/06/24 18:49		

	Type	Hits	Search Text
32	BRS	44	5250843.URPN.
33	BRS	481	257/680.ccls.
34	BRS	2470	257/\$.ccls. and core
35	BRS	0	((257/706,712,720.ccls. and (ic chip die)) and (plastic (encapsulant adj material))) and (build near3 layer)) and core near5 openings
36	BRS	191	257/\$.ccls. and core near3 (chip die IC)
37	IS&R	14	((("6238954") or ("6388328") or ("6310400") or ("6303464") or ("5909635") or ("6087728"))).PN.
38	IS&R	46	((("4897154") or ("4980018") or ("5035768") or ("5167760") or ("5343524") or ("5612254") or ("5350484") or ("6312830") or ("5394876") or ("6192406") or ("5857973") or ("5994660") or ("6160340") or ("6229216") or ("6271469") or ("6154366") or ("6219243") or ("6355534") or ("6251036"))).PN.
39	BRS	37	("3740920"   "4705917"   "4925024"   "5353498"   "5414214"   "5422513"   "5497033"   "5527741"   "5703400"   "5745984"   "5790378"   "5894107"   "6154366"   "6192578").PN.
40	BRS	3	6154366.URPN.
41	BRS	3044	chip near3 (pocket cavity)
42	BRS	336	(chip near3 (pocket cavity)) and (heat adj sink)
43	IS&R	2	("6271469").PN.
44	BRS	329	package adj core

	DBs	Time Stamp	Comments	Error Definition
32	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/06/24 18:54		
33	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/06/24 20:04		
34	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/06/24 20:05		
35	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/06/24 20:07		
36	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/06/24 20:16		
37	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/06/24 20:29		
38	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/06/24 20:56		
39	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/06/24 20:54		
40	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/06/24 20:56		
41	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/06/24 20:57		
42	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/06/25 13:33		
43	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/06/25 13:36		
44	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/06/25 14:02		

	Type	Hits	Search Text
45	BRS	31	257/668.ccls. and (CSP (chip adj side adj package))
46	BRS	182303	257/668.ccls. (dielectric insulation) and open\$3
47	BRS	29405	(257/668.ccls. (dielectric insulation) and open\$3) and (chip die)
48	BRS	910	257/668.ccls.
49	BRS	6912	(dielectric BT FR4) near3 open\$3
50	BRS	36	((dielectric BT FR4) near3 open\$3) near3 (chip die IC)
51	BRS	0	(BT FR4) near3 (open\$3 hole cavity) near3 (heat adj (sink spreader element))
52	IS&R	2	("5250347").PN.
53	BRS	403	(CSP (chip adj scale adj package)) and (257/\$.ccls 438/\$.ccls.)
54	BRS	36	((CSP (chip adj scale adj package)) and (257/\$.ccls 438/\$.ccls.)) and (heat adj sink)

	DBs	Time Stamp	Comments	Error Definition
45	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/06/25 14:21		
46	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/06/25 14:21		
47	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/06/25 14:21		
48	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/06/25 14:31		
49	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/06/25 14:33		
50	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/06/25 14:38		
51	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/06/25 15:09		
52	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/06/25 14:43		
53	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/06/25 15:12		
54	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/06/25 15:12		